



Product Change Notification

Change Notification #: 117838 - 00
Change Title: Intel® Ethernet Network Adapter Open Compute Project (OCP) 3.0: X710T2LOCPV3G1P, MM#9999MK, X710T2LOCPV3, MM#9999MJ and X710T2LOCPV3G1L, MM#99A01H, PCN 117838-00, Product Design, Label, Firmware Update and Label Change
Date of Publication: October 23, 2020

Key Characteristics of the Change:

Product Design, Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	December 7, 2020
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Description of Change to the Customer:

1. The Intel® Ethernet Network Adapter X710-T2L and Intel® Ethernet Network Adapter X710-T2L for OCP 3.0 will undergo the following changes:
 - a. The Fortville (FVL) version 8.1 Non-Volatile Memory (NVM) releases include new PHY firmware that optimized the tuning of the timing PLLs when Energy-Efficient Ethernet (EEE) is enabled to sufficiently address issues documented in TA-246. Also, the NVM releases contain firmware support for asserting the sideband scan chain signals required by OCP 3.0 Specifications to address issues documented.
 - b. Customers who wish to update their older boards to the new firmware can access the NVM update package here: <https://downloadcenter.intel.com/download/22283/Intel-Ethernet-Adapter-Complete-Driver-Pack>
2. Update the Standby thermal for AUX power state (S5) for OCP 3.0 platforms for Intel Ethernet OCP 3.0 adapters which requires specific cooling requirements.
3. Label changes:
 - a. Intel will update the Intel Serial Number label to change the Intel PBA number to reflect the "Post Change PBA" part number, as documented in the "Products Affected / Intel Ordering Codes" section.
 - b. Intel will update all the Intel outer box/disti labels on packaging to change Intel Top Assembly number to reflect the new "Post Change TA" part number, as documented in the "Products Affected / Intel Ordering Codes" section.

Customer Impact of Change and Recommended Action:

Intel anticipates no functional impact to customer but encourages customer to understand the changes and determine the impact to their operations if any.

You can expect to receive mixed inventory until current inventory levels have been depleted.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
X710T2LOCPV3	9999MJ	K64401-003	K58515-003	K64401-004	K58515-004
X710T2LOCPV3G1P	9999MK	K58360-003	K31193-007	K58360-004	K31193-008
X710T2LOCPV3G1L	99A01H	K88639-002	K87346-003	K88639-003	K87346-004

PCN Revision History:

Date of Revision:

October 23, 2020

Revision Number:

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Reason:

Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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